

3.4mm RIGHT ANGLE LED INDICATOR

Part Number: WP138A8QMP/YD/TG Yellow

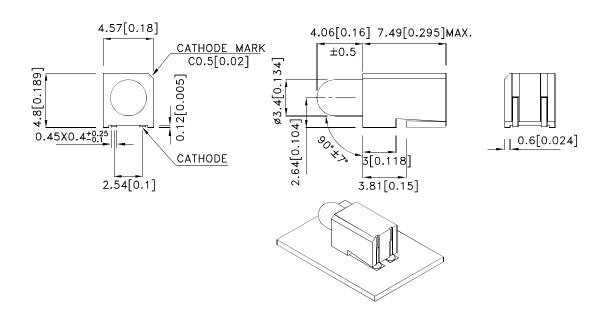
Features

- Surface mount type.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Package:1000pcs / reel.
- Moisture sensitivity level : level 3.
- Housing UL rating:94V-0.
- Housing material: PPA.
- · High temperature resistant housing.
- High glass transition temperature epoxy.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 SPEC NO: DSAF8371
 REV NO: V.7B
 DATE: MAR/19/2013
 PAGE: 1 OF 6

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: F.Cui
 ERP: 1102000504

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
WP138A8QMP/YD/TG	Yellow (GaAsP/GaP)	Yellow Diffused	4	8	60°

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions			
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA			
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA			
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA			
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz			
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA			
lR	Reverse Current	Yellow		10	uA	V _R =5V			

Notes:

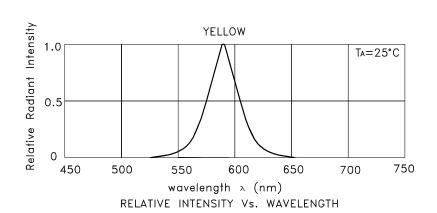
- NWavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

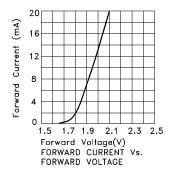
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

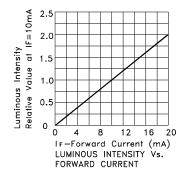
SPEC NO: DSAF8371 **REV NO: V.7B** DATE: MAR/19/2013 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.Cui ERP: 1102000504

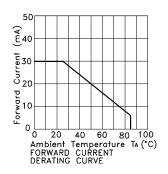


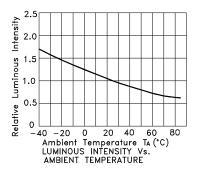
Yellow

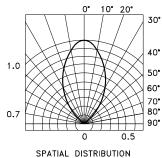
WP138A8QMP/YD/TG







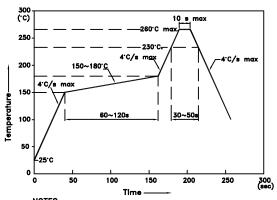




SPEC NO: DSAF8371 APPROVED: WYNEC REV NO: V.7B CHECKED: Allen Liu DATE: MAR/19/2013 DRAWN: F.Cui PAGE: 3 OF 6 ERP: 1102000504

WP138A8QMP/YD/TG

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

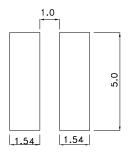
1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

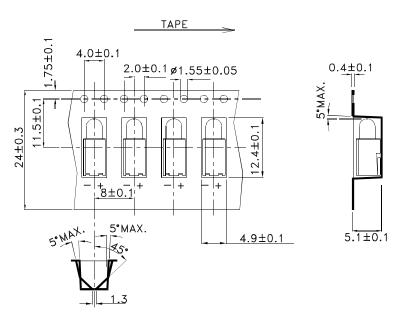
3.No more than once.

Recommended Soldering Pattern

(Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)



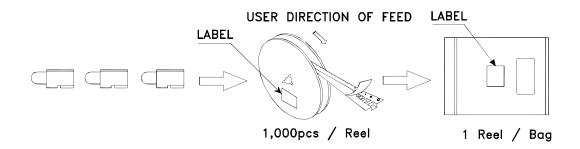
SPEC NO: DSAF8371 APPROVED: WYNEC

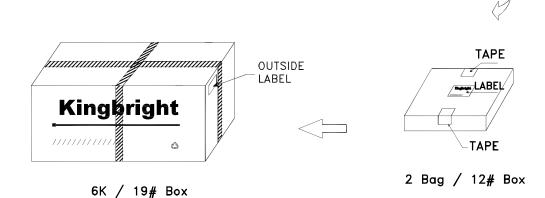
REV NO: V.7B CHECKED: Allen Liu DATE: MAR/19/2013 DRAWN: F.Cui

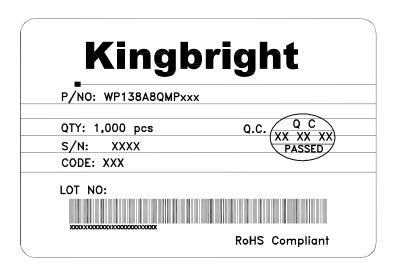
PAGE: 4 OF 6 ERP: 1102000504

PACKING & LABEL SPECIFICATIONS

WP138A8QMP/YD/TG



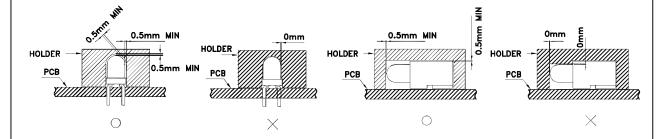




SPEC NO: DSAF8371 APPROVED: WYNEC REV NO: V.7B CHECKED: Allen Liu DATE: MAR/19/2013 DRAWN: F.Cui PAGE: 5 OF 6 ERP: 1102000504

PRECAUTIONS

- 1.A moisture barrier bag (MBB) containing LEDs shall be kept in an environment with temperature below 40°C and humidity below 90% RH.
 - A MBB shall be kept sealed until the LEDs contained in that bag are to be used immediately. Storge in an environment with temperature $5\sim30^{\circ}\text{C}$ and humidity below 60% RH.
- 2.After a MBB has been opened, all LEDs contained in that bag shall complete soldering process within according to the conditions listed on the Kingbright MBB.
- 3.If the 10% spot of a humidity indicator card (HIC) indicates wet, LEDs shall be baked according to the conditions listed on the Kingbright MBB.
- 4.During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 5. The tip of the soldering iron should never touch the lens epoxy.
- 6.After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
- 7.If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

 SPEC NO: DSAF8371
 REV NO: V.7B
 DATE: MAR/19/2013
 PAGE: 6 OF 6

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: F.Cui
 ERP: 1102000504